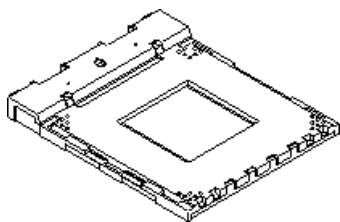



Part Number: 500210-4786

1.27mm Pitch Micro PGA Socket for Mobile Pentium* 4, Ball Grid Array (BGA) Mount, ZIF, 478 Circuits, Key Version C, with Pick and Place Cover, Tray Package, Lead-Free



Series Image - Reference only

Status:	OBSOLETE
Replacement:	Contact Molex
Series:	500210
Category:	Processor Sockets

Mates With Part(s):

Intel Mobile Celeron* Processor-M, Intel Mobile Pentium* 4 Processor

Product Environmental Compliance

EU RoHS: ELV and RoHS Compliant

China RoHS:

REACH SVHC:

Low-Halogen Status: Not Reviewed

Part Detail

General	
Status	Obsolete
Category	Processor Sockets
Series	500210
Comments	ZIF, with Pick and Place Cover
Component Type	Socket
Product Name	Micro PGA
Physical	
Circuits (Loaded)	478
Circuits (maximum)	478
Color - Resin	Black, Blue (Light)
Durability (mating cycles max)	50
Material - Metal	Copper-Nickel-Silicon, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Nickel
Material - Resin	High Temperature Thermoplastic
Packaging Type	Tray
Pitch - Mating Interface	1.27mm
Plating min - Mating	0.254µm
Plating min - Termination	1.270µm
Temperature Range - Operating	-20°C to +90°C
Termination Interface: Style	Surface Mount
Electrical	
(Please review the Product Specification for specific details.)	
Current - Maximum per Contact	0.5A
Voltage - Maximum	100V
Material Info	

Application Tooling

Tooling specifications and manuals are found by selecting the products below.

Crimp Height Specifications are then contained in the Application Tooling Specification document.

Previously Available Application Tooling

[Check our list of old tooling that used to be available for this part](#)

